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(12) **United States Design Patent**
Hara

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(54) **SEMICONDUCTOR MODULE**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/123, 133, 146, 147, 158, 182, 184,
D13/199
CPC H01L 28/06; H01L 28/07; H01L 28/08;
H01L 25/07; H01L 25/16; H01L 25/18;
H01L 23/00; H01L 23/31; H05K 1/18;
H05K 7/00; H05K 7/20; H02M 7/00
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a first embodiment of a semiconductor module showing my new design;

FIG. 2 is a rear, bottom and left side perspective view thereof;

FIG. 3 is a front view thereof;

FIG. 4 is a rear view thereof;

FIG. 5 is a top plan view thereof;

FIG. 6 is a bottom plan view thereof;

FIG. 7 is a right side view thereof, the left side view being a mirror image of FIG. 7;

FIG. 8 is a front, top and right side perspective view of a second embodiment of a semiconductor module showing my new design;

FIG. 9 is a rear, bottom and left side perspective view thereof;

FIG. 10 is a front view thereof;

FIG. 11 is a rear view thereof;

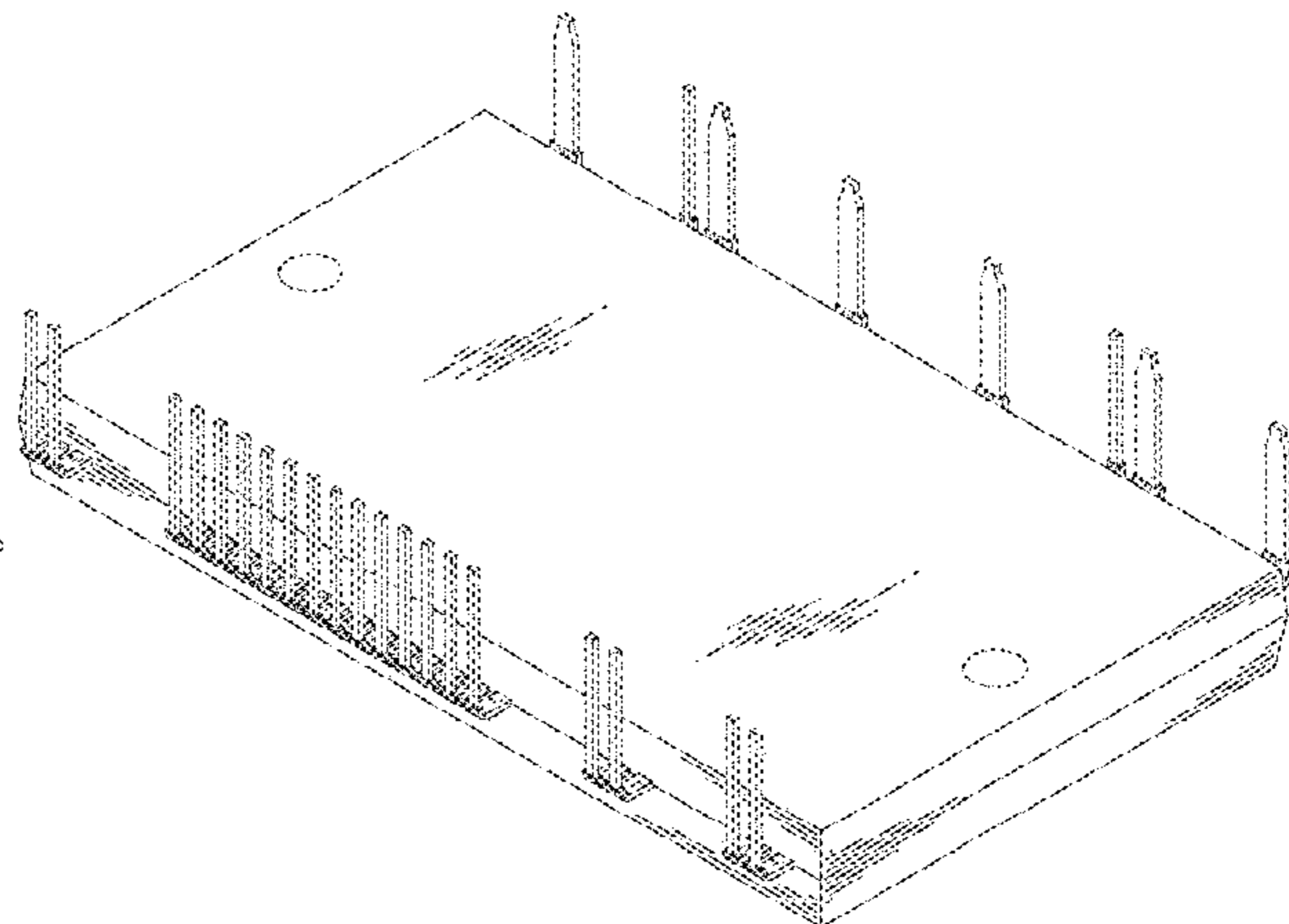
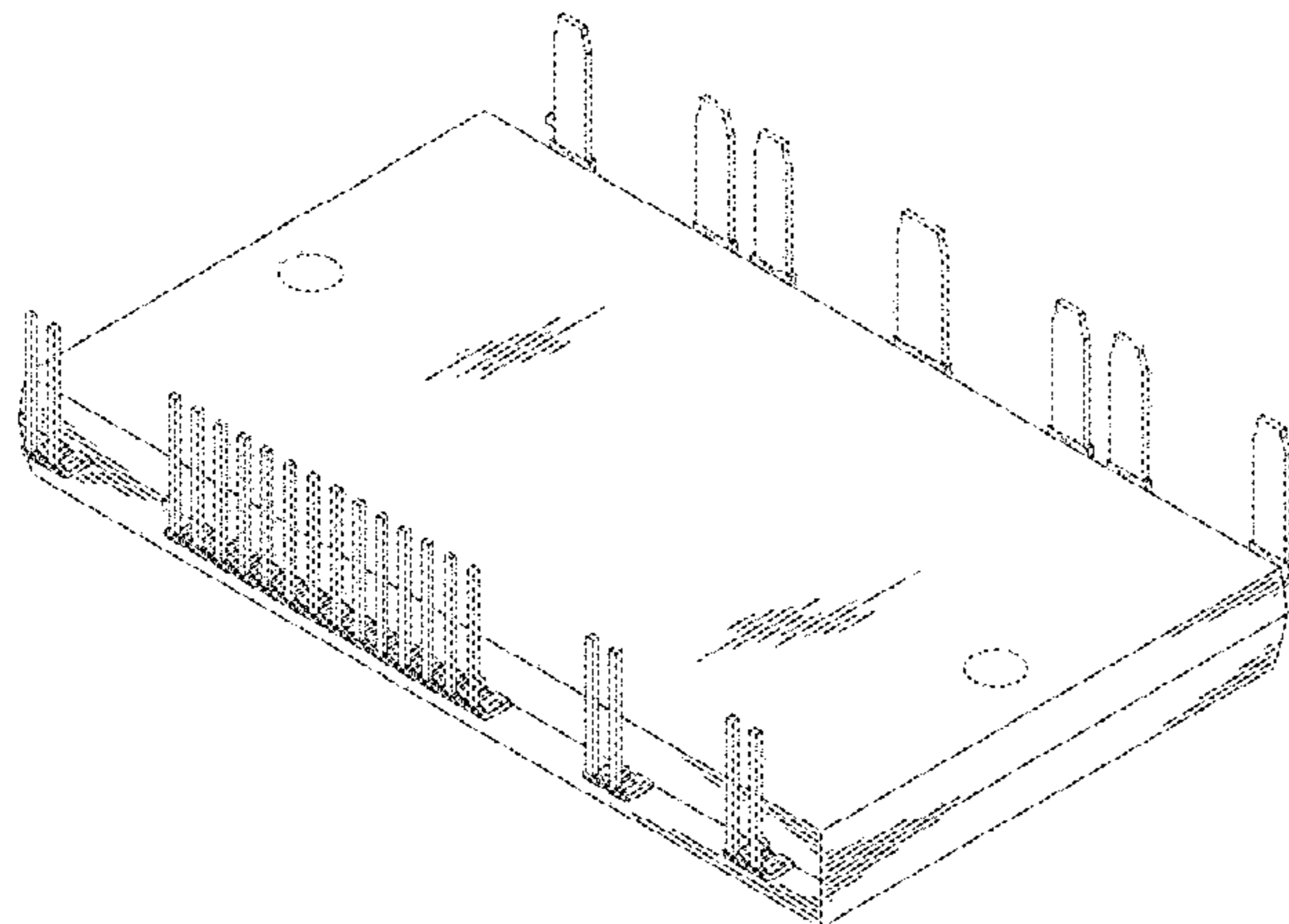
FIG. 12 is a top plan view thereof;

FIG. 13 is a bottom plan view thereof; and,

FIG. 14 is a right side view thereof, the left side view being a mirror image of FIG. 14.

The broken lines illustrate portions of the semiconductor module that form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design.

1 Claim, 14 Drawing Sheets



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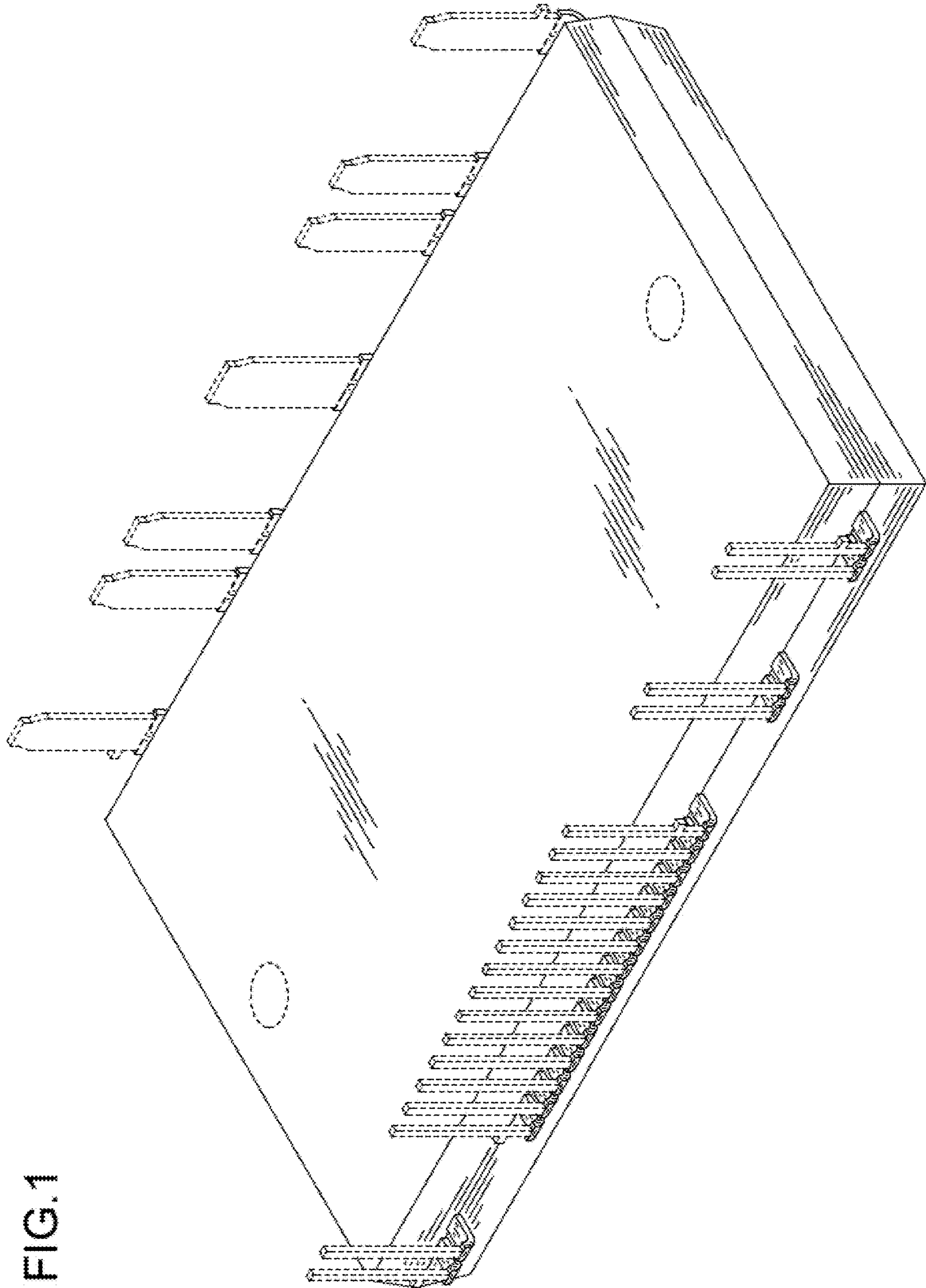


FIG. 1

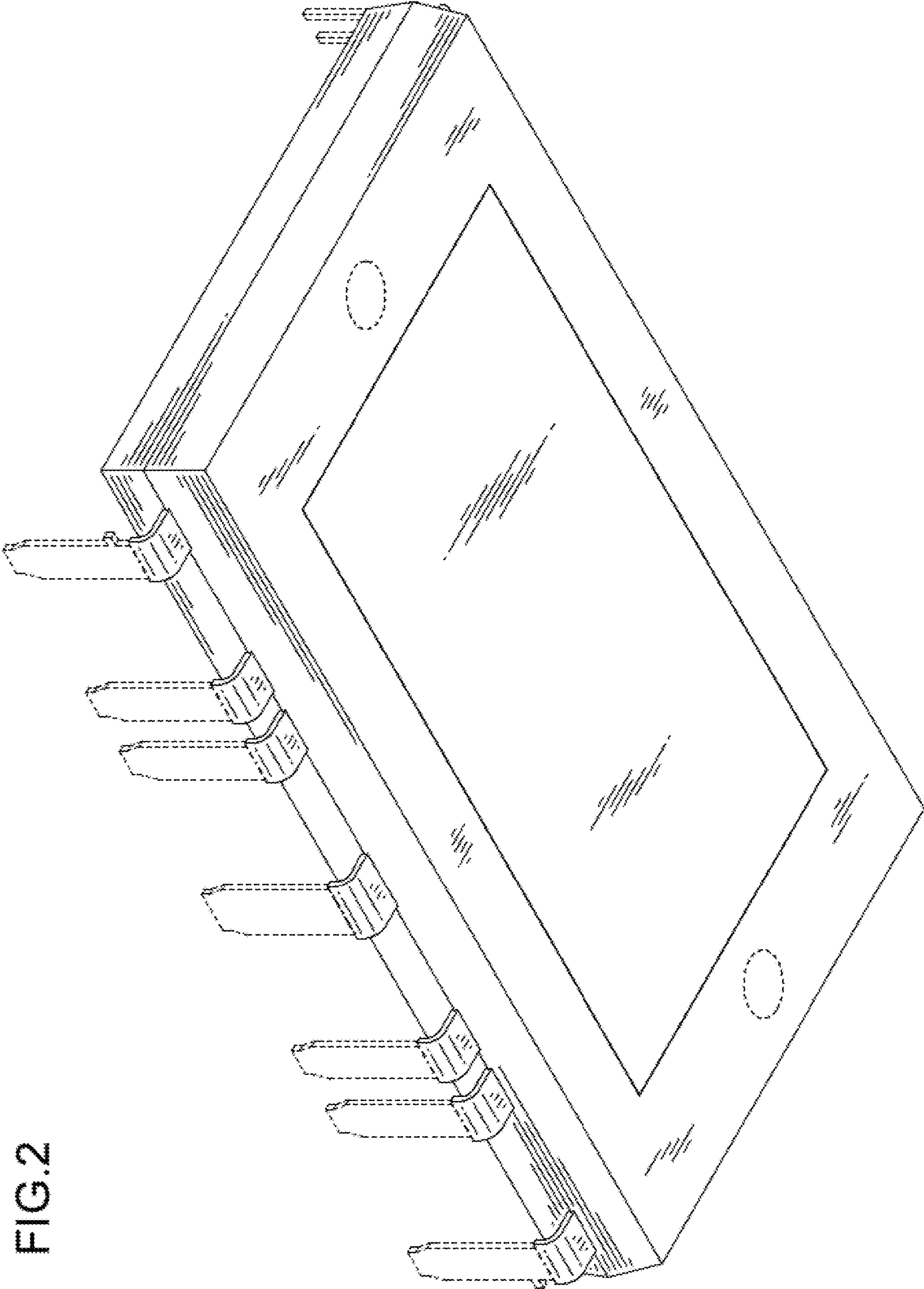


FIG.2

FIG. 3

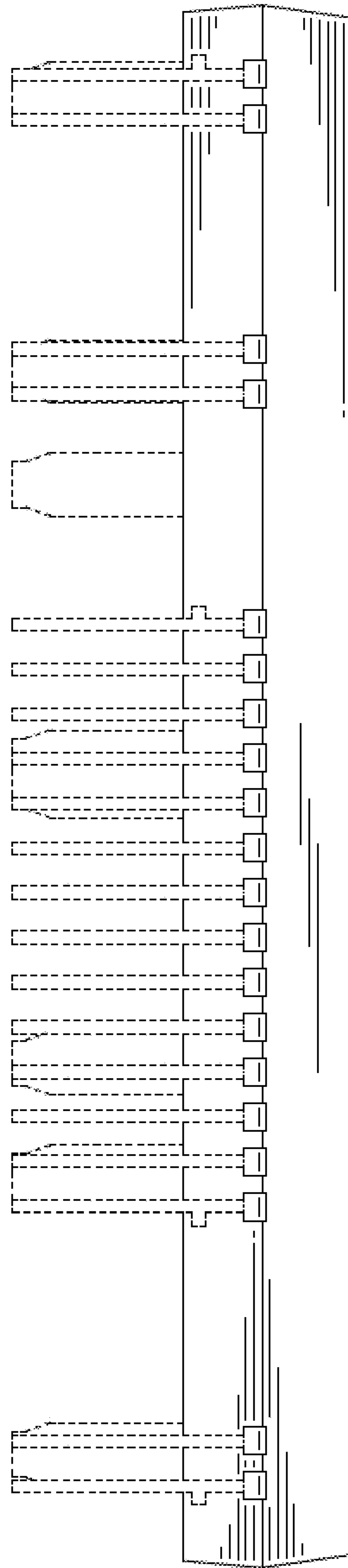


FIG.4

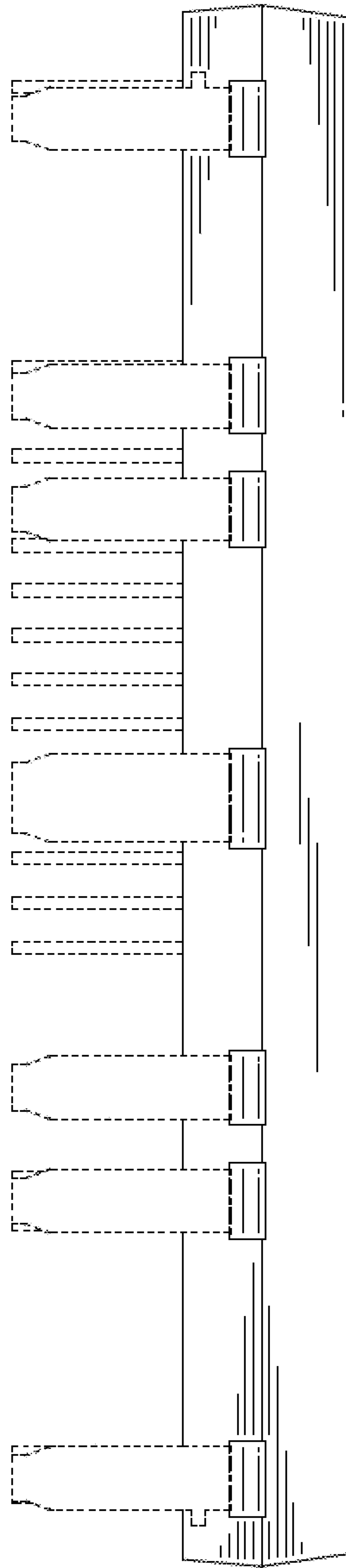


FIG. 5

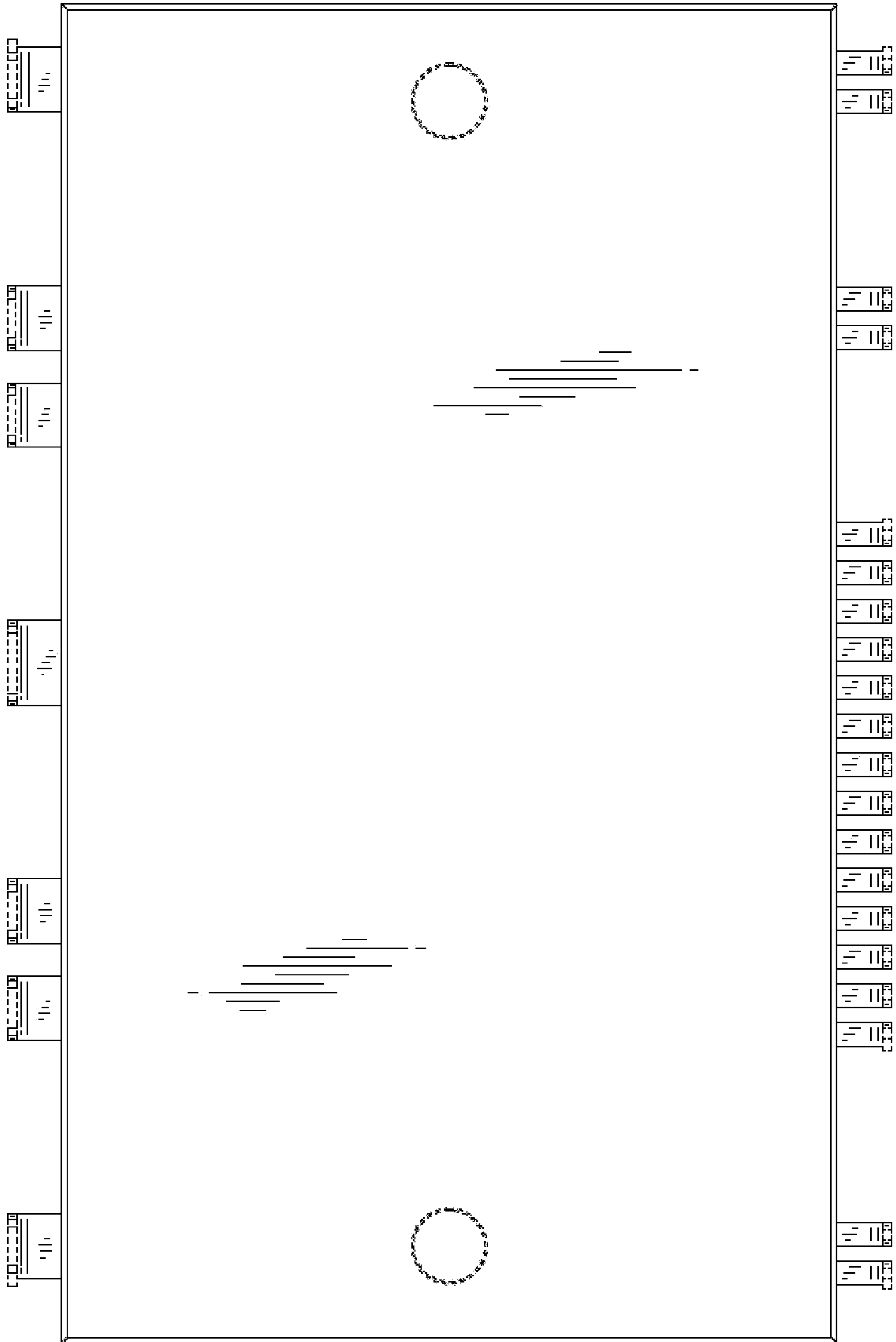
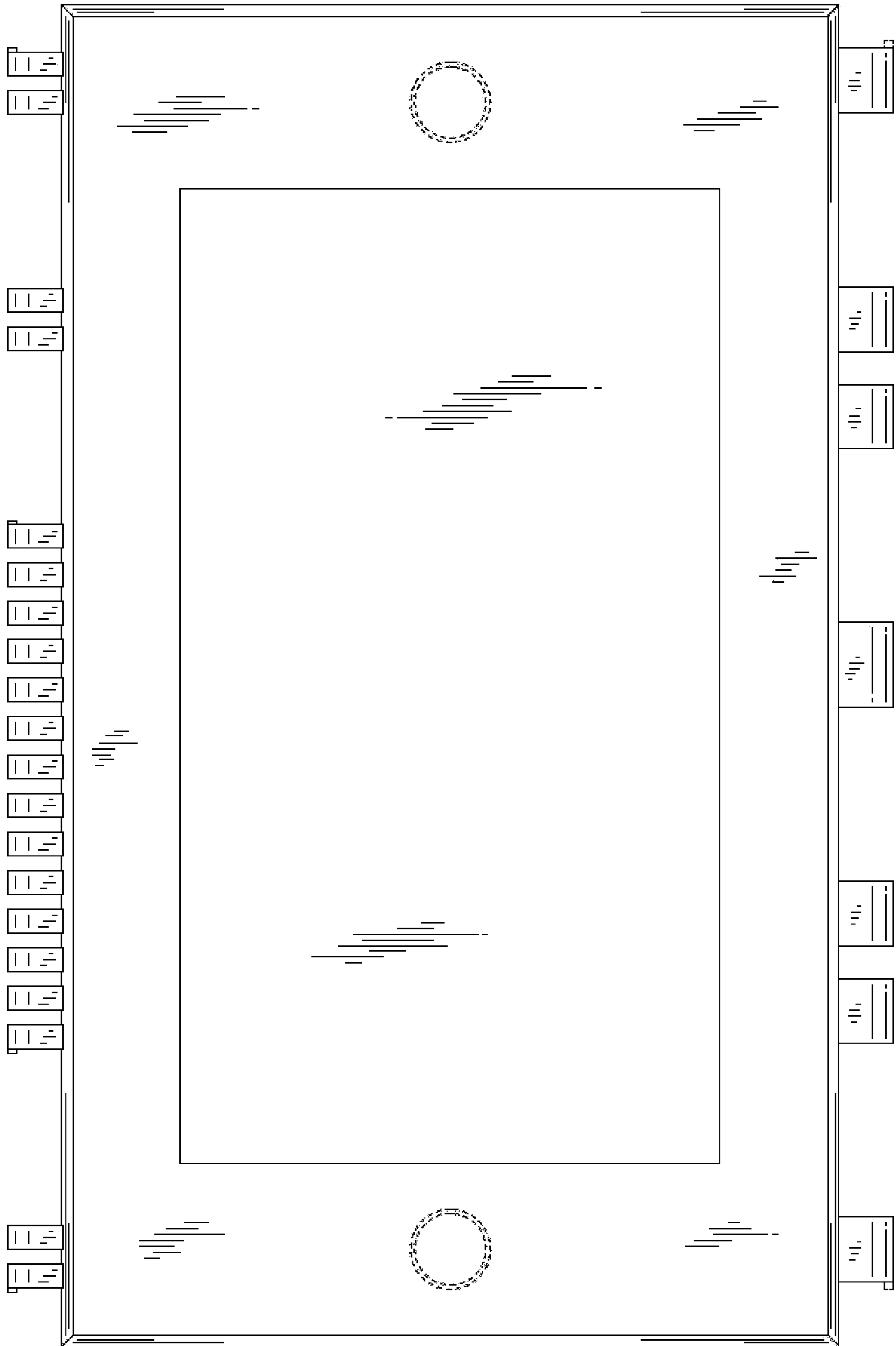


FIG. 6



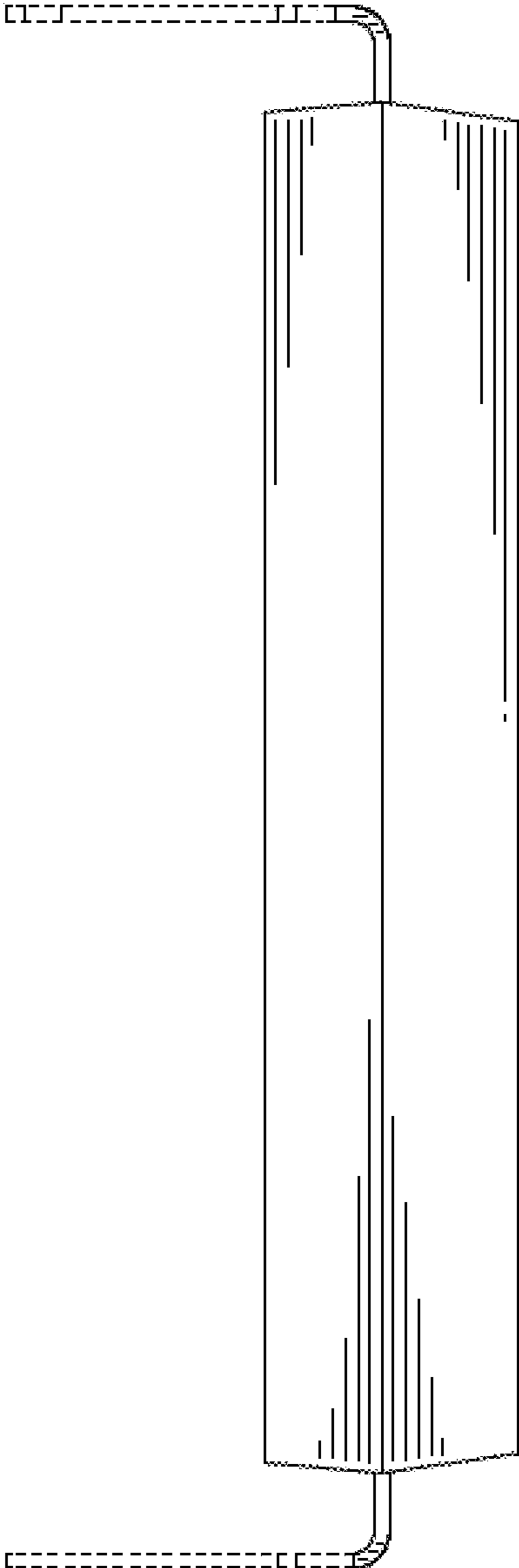


FIG.7

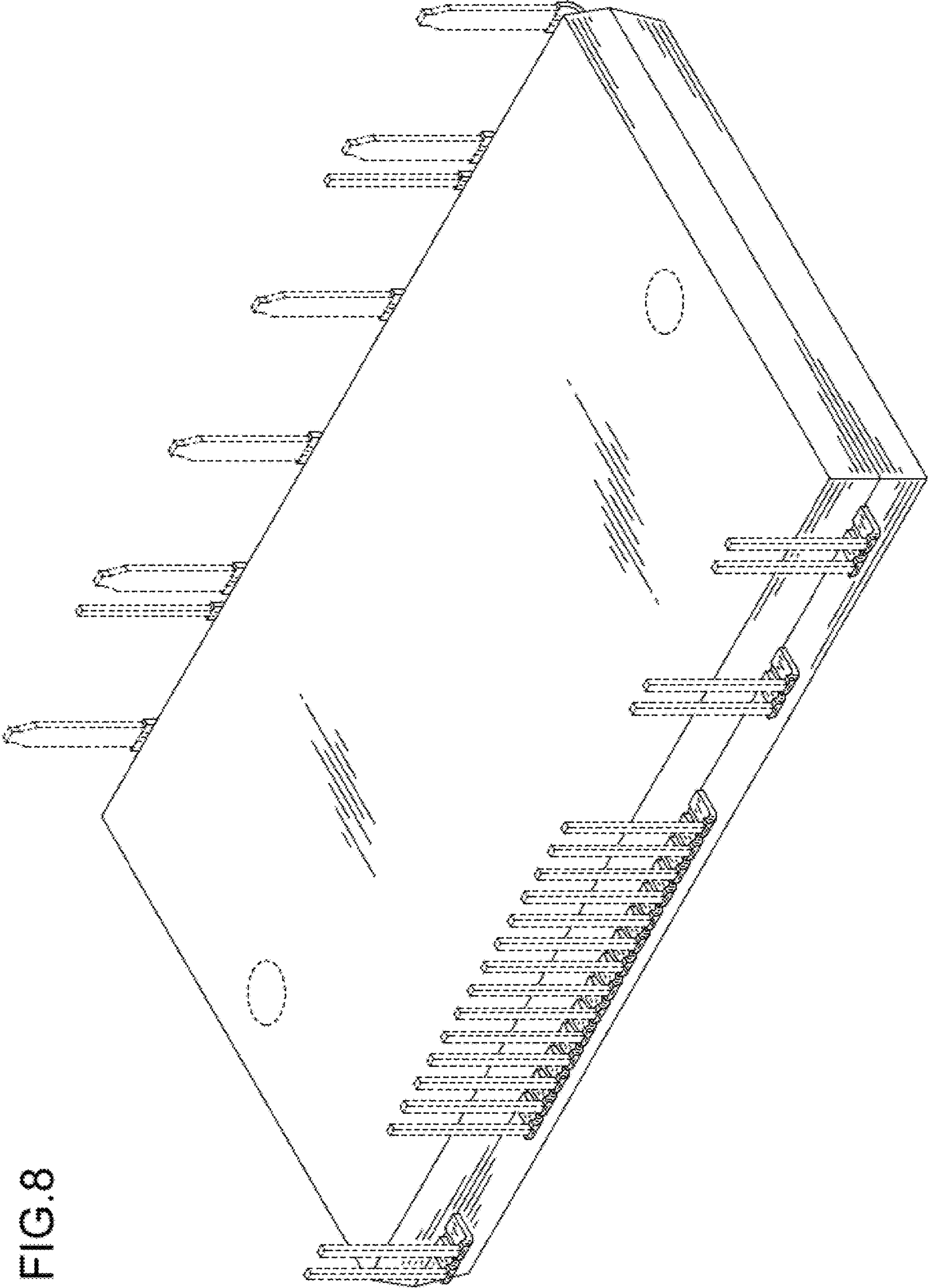


FIG.8

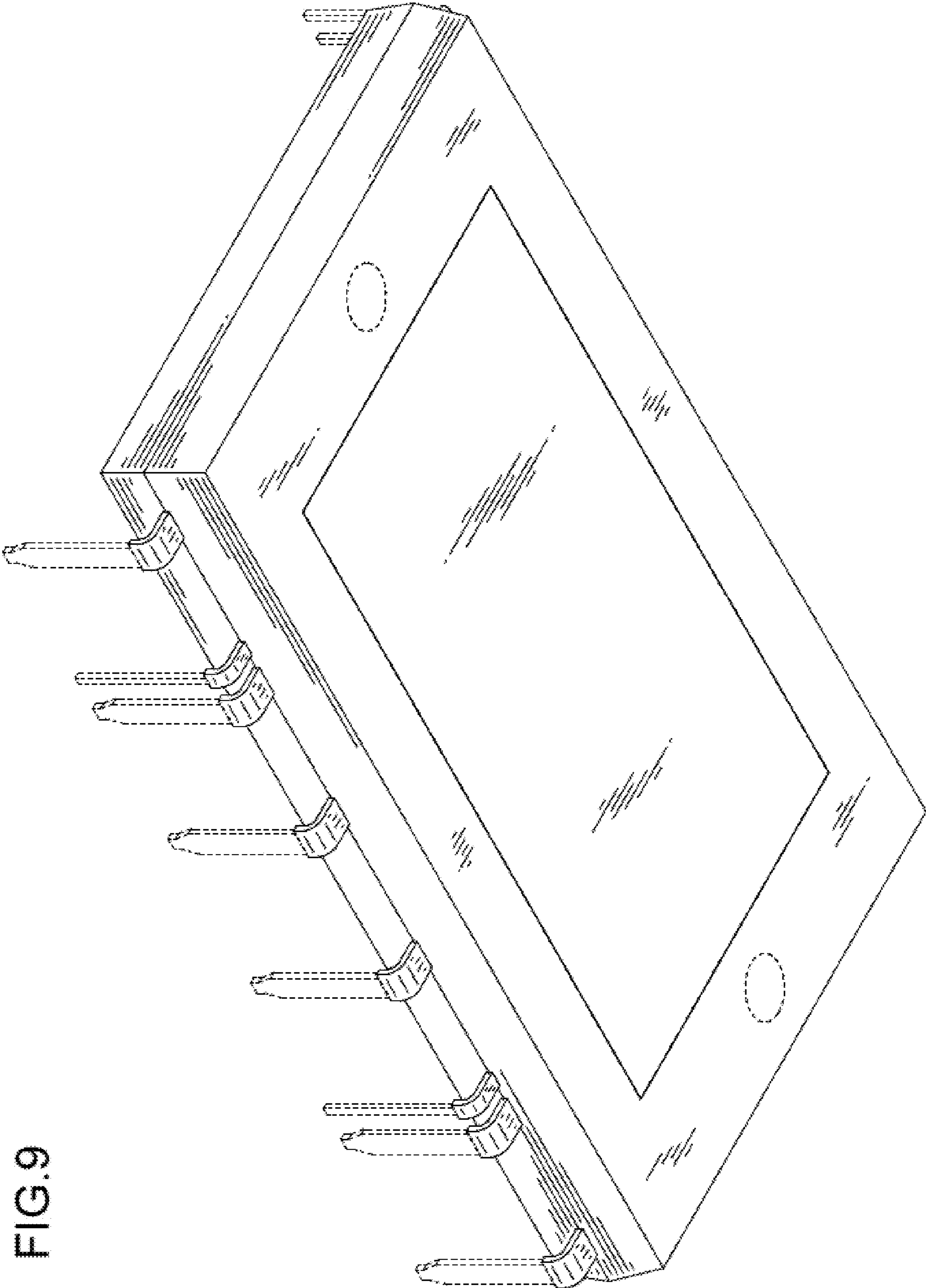


FIG. 9

FIG.10

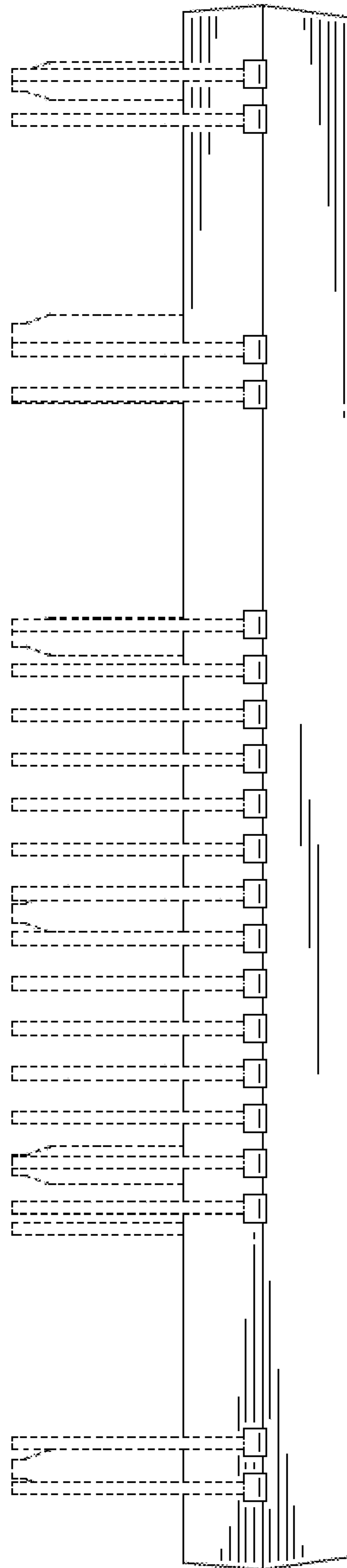


FIG.11

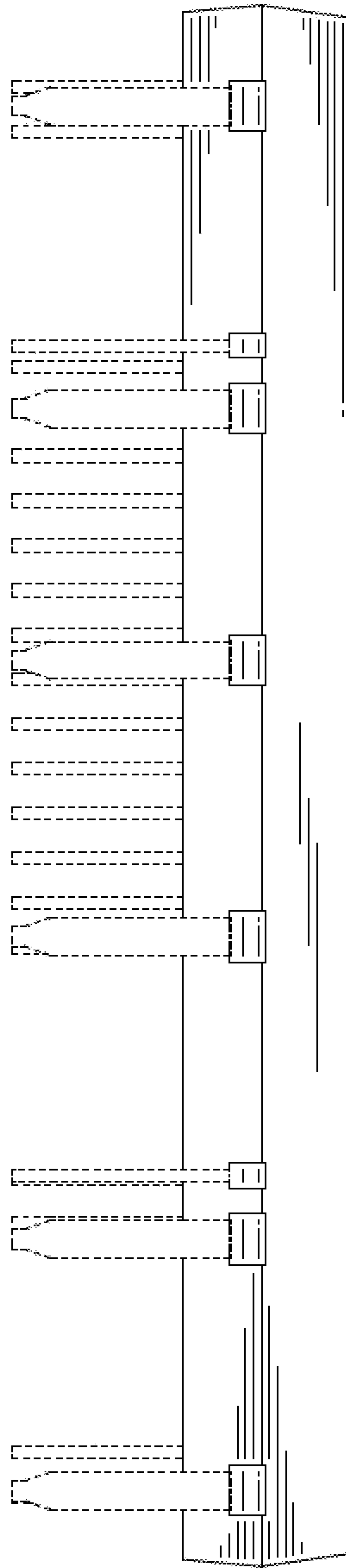


FIG.12

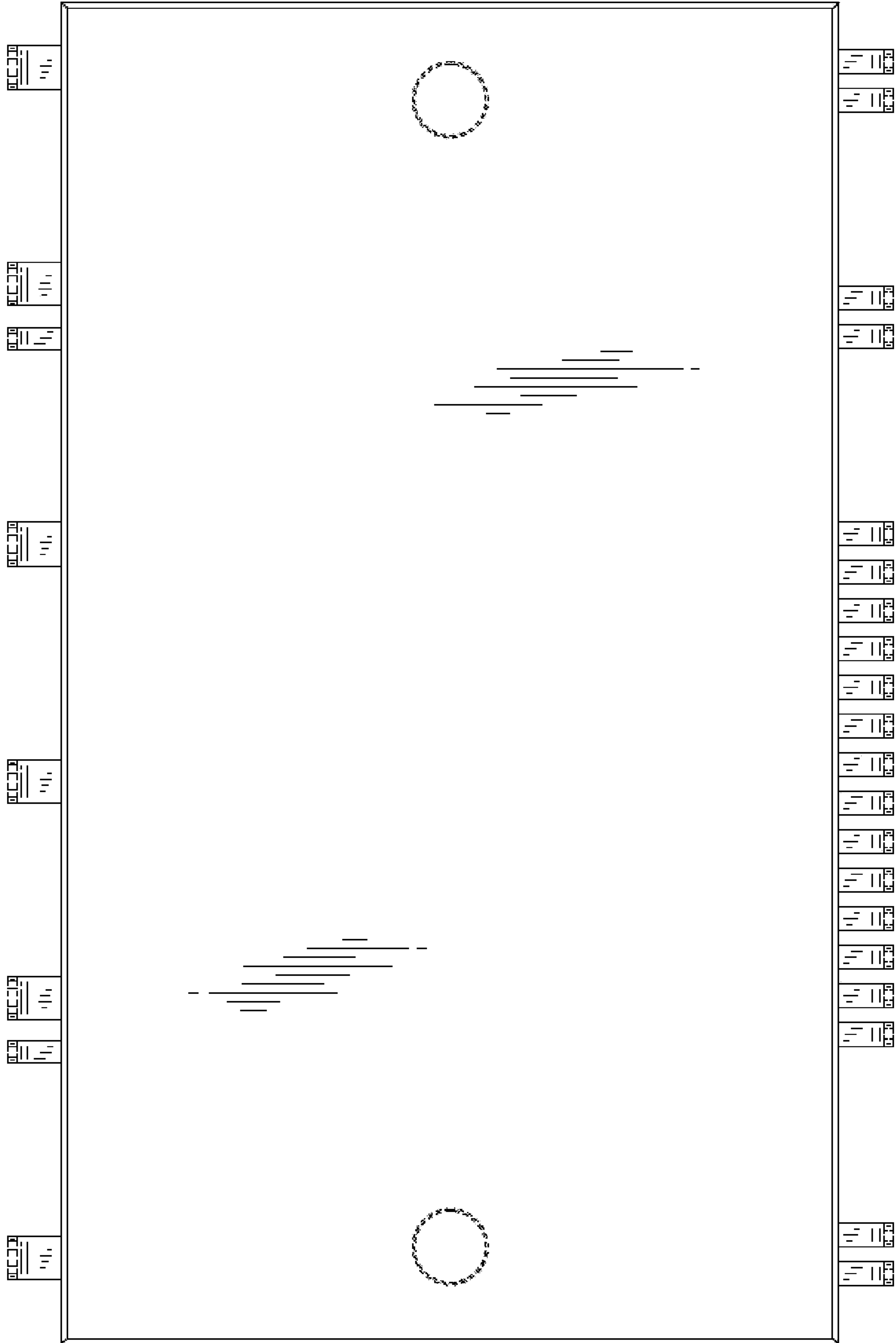
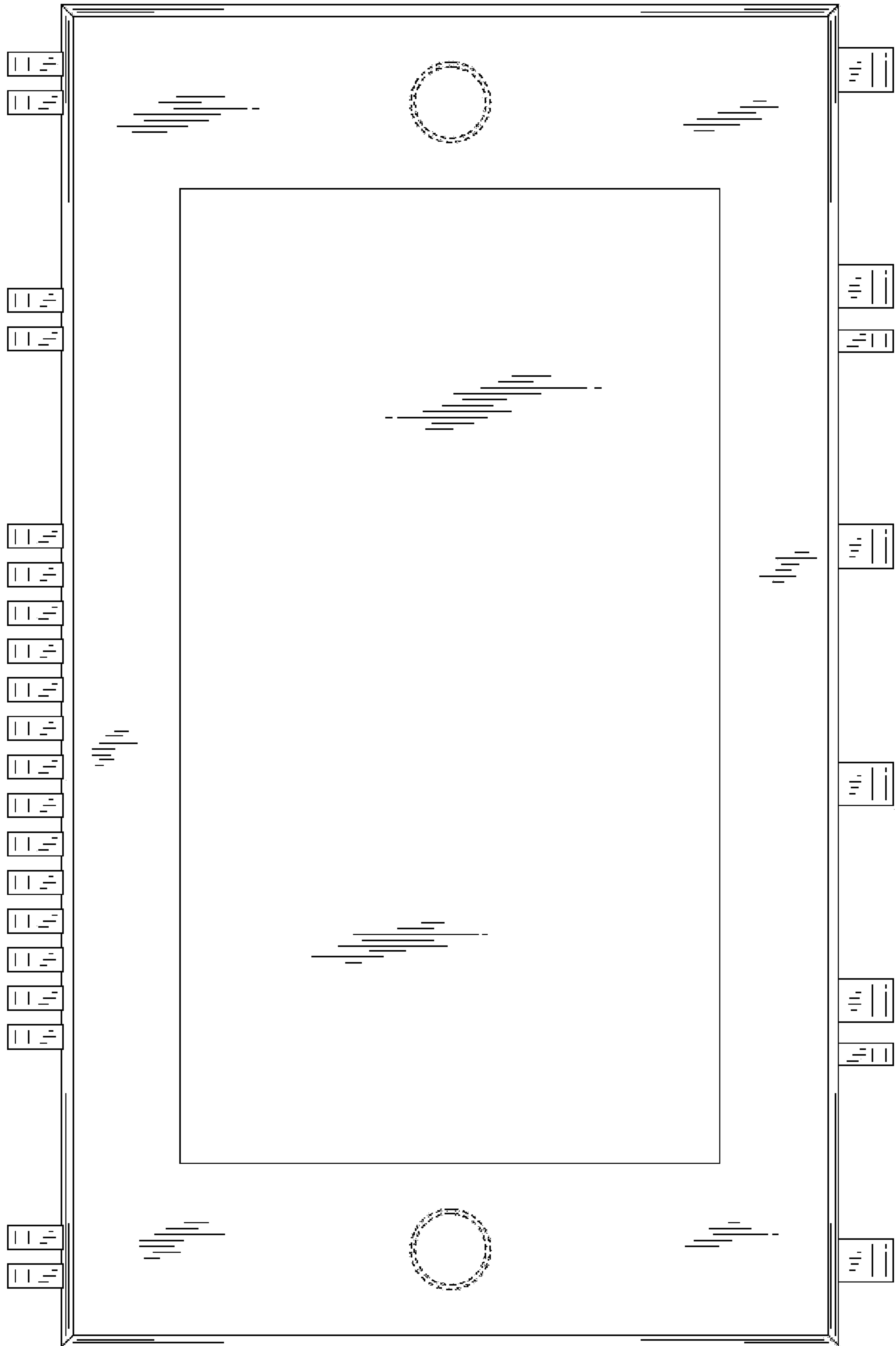


FIG.13



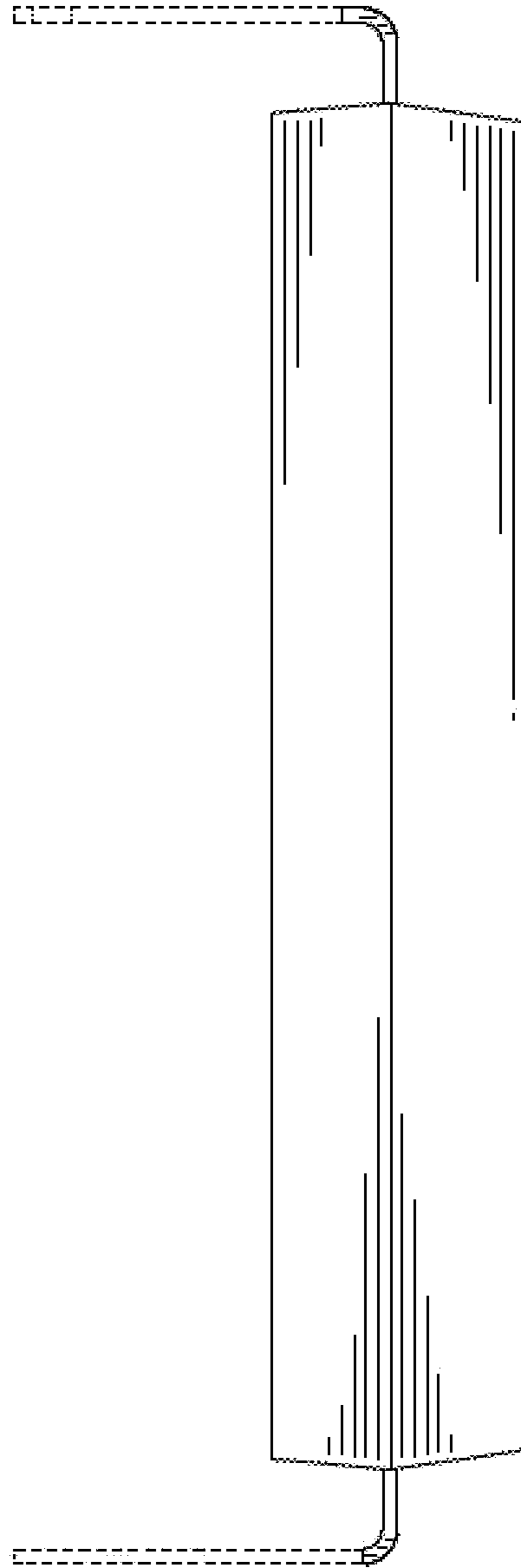


FIG.14